PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YAPING LIU	08/07/2017
TATSUROU YASHIKI	08/22/2017
HIDEHARU TANAKA	08/23/2017
NOBUHIRO TOTTORI	08/23/2017
YORIYUKI SHINADA	08/23/2017

RECEIVING PARTY DATA

Name:	HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.
Street Address:	3, KANDA NERIBEI-CHO
City:	CHIYODA-KU, TOKYO
State/Country:	JAPAN
Postal Code:	1010022

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15555427

CORRESPONDENCE DATA

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Address Line 4: WASHINGTON, D.C. 20002

ATTORNEY DOCKET NUMBER:	107259.PA344US
NAME OF SUBMITTER:	MICHAEL H. JACOBS
SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	09/06/2017

Total Attachments: 5
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ASSIGNMENT
（譲 渡 証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me, citizen of Japan, by **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**, a corporation organized under the laws of **Japan**, located at **3, Kanda Neribei-cho, Chiyoda-ku, Tokyo 1010022, JAPAN**, receipt of which is hereby acknowledged I do hereby sell and assign to said **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

NETWORK SIMULATION DEVICE, NETWORK SIMULATION METHOD, AND NETWORK SIMULATION PROGRAM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**.

,Signed on the date(s) indicated aside signatures:

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1) Yaping LIU **Yaping LIU**	August 7, 2017
2) **Tatsurou YASHIKI**	

ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me, citizen of Japan, by **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**, a corporation organized under the laws of **Japan**, located at **3, Kanda Neribei-cho, Chiyoda-ku, Tokyo 1010022, JAPAN**, receipt of which is hereby acknowledged I do hereby sell and assign to said **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **HITACHI INDUSTRIAL EQUIPMENT SYSTEMS CO., LTD.**.

,Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) ______________________ **Yaping LIU**	______________________
2) Tatsurou Yashiki **Tatsurou YASHIKI**	August 22, 2017

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
3) Hideharu Tanaka **Hideharu TANAKA**	August 23, 2017
4) **Nobuhiro TOTTORI**	
5) **Yoriyuki SHINADA**	

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
3) ______________ **Hideharu TANAKA**	______________
4) Nobuhiro Tottori **Nobuhiro TOTTORI**	August 23, 2017
5) ______________ **Yoriyuki SHINADA**	______________

INVENTOR(S) (発明者フルネームサイン)	Date Signed （署名日）
3) ______________________ **Hideharu TANAKA**	______________
4) ______________________ **Nobuhiro TOTTORI**	______________
5) Yoriyuki Shinada **Yoriyuki SHINADA**	August 23, 2017